

- Please note that the Lyra-S module is a System in Package (SiP) Integrated Circuit (IC). The module is encapsulated in epoxy which cannot be removed without destroying the module, therefore internal photos with the shield removed are not possible.

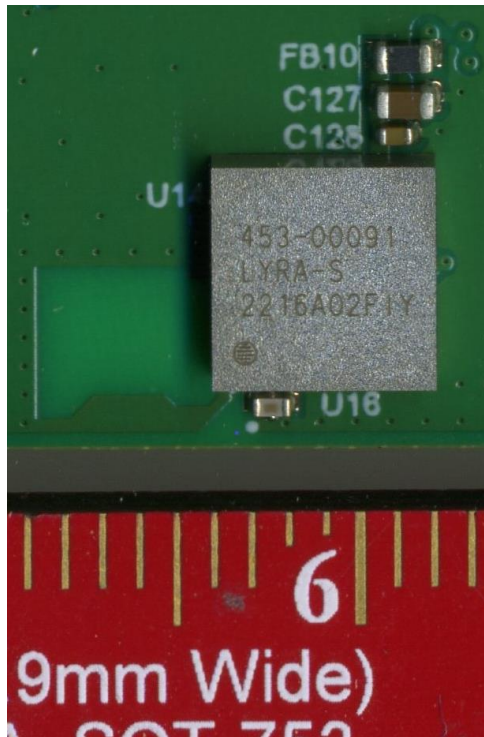


Figure 1. Lyra-S BLE module and antenna close-up